

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

Page 35

Please amend the paragraph beginning at line 3, through line 10 as indicated below:

The polymerizable composition of the invention is low in viscosity and the resin molded product of the invention is excellent in dielectric characteristics (a high dielectric constant and a low dielectric loss tangent), a low linear expansion coefficient, mechanical strengths, heat resistance and the like. The crosslinked resin complex above is high in adhesion strength between the ~~thermoplastic~~ crosslinked resin of the invention and the other material.